

IN THE SPECIFICATION

Please amend the specification as follows:

Page 10, line 10, please delete "etch" and insert --etched--.

5 Page 11, line 17, please insert --(see Figure 3)-- after "108a".

Page 12, line 13, please insert --(see Figure 4)-- after "108b".

Page 12, line 16, please insert -- as shown in Figure 4,-- after "104".

Page 13, line 3, please delete "exposed" and insert --expose--.

Page 13, line 11, please insert --as shown in Figure 5-- after "photoresist".

10 Page 13, line 11, please delete "As shown in Figure 10," and insert Figure 10A

B, illustrates subsequent fabrication in which--.

Page 15, line 12, please delete "etch" and insert --etched--.

IN THE CLAIMS

15 All claims pending after this amendment are listed below. Please amend the claims as follows:

PLEASE CANCEL CLAIMS 1-20.

20 21. (Amended) A multi-layer dielectric layer over a substrate for use in dual-damascene applications, comprising:

a barrier layer disposed over the substrate;

an inorganic dielectric layer disposed over the barrier layer; and

25 a low dielectric constant layer disposed directly over the inorganic dielectric layer;

wherein the [inorganic] low dielectric constant layer is configured to receive metallization line trenches and the [low] inorganic dielectric [constant] layer is configured to receive vias during a dual-damascene process.